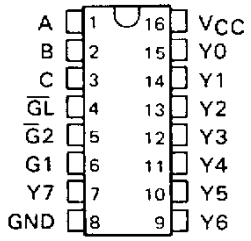
SCLS125

SN54HC237, SN74HC237
3-LINE TO 8-LINE DECODERS/DEMULTIPLEXERS WITH ADDRESS LATCHES

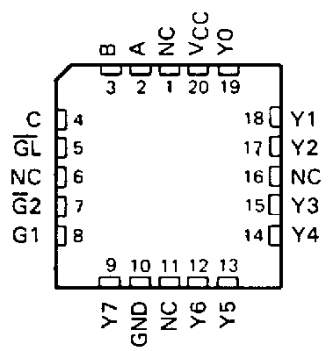
D2804, MARCH 1984—REVISED JUNE 1989

- Combines Decoder and 3-Bit Address Latch
- Incorporates 2 Output Enables to Simplify Cascading
- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs
- Dependable Texas Instruments Quality and Reliability

SN54HC237 . . . J PACKAGE
SN74HC237 . . . D† OR N PACKAGE
(TOP VIEW)



SN54HC237 . . . FK PACKAGE
(TOP VIEW)



NC—No internal connection

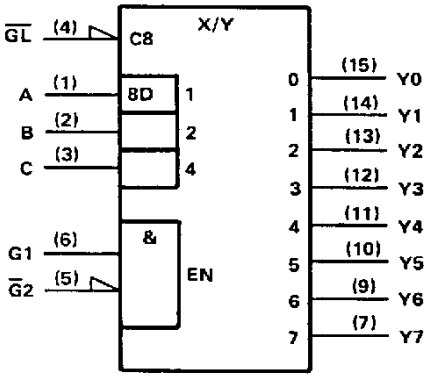
†Contact the factory for D availability.

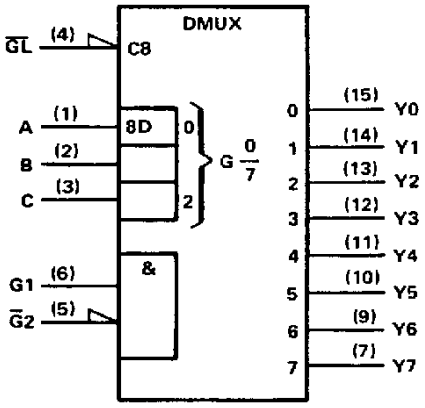
description

The 'HC237 is a three-line to eight-line decoder/demultiplexer with latches on the three address inputs. When the latch-enable (GL) is low, the 'HC237 acts as a decoder/demultiplexer. When GL goes from low to high, the address present at the select inputs (A, B, and C) is stored in the latches. Further address changes are ignored as long as GL remains high. The output enable controls, G1 and G2, control the outputs independently of the select or latch-enable inputs. All of the outputs are forced low if G1 is low or G2 is high. The 'HC237 is ideally suited for implementing glitch-free decoders in strobed (stored-address) applications in bus-oriented systems.

The SN54HC237 is characterized for operation over the full military temperature range of −55°C to 125°C. The SN74HC237 is characterized for operation from −40°C to 85°C.

logic symbols (alternatives)‡





‡These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, and N packages.

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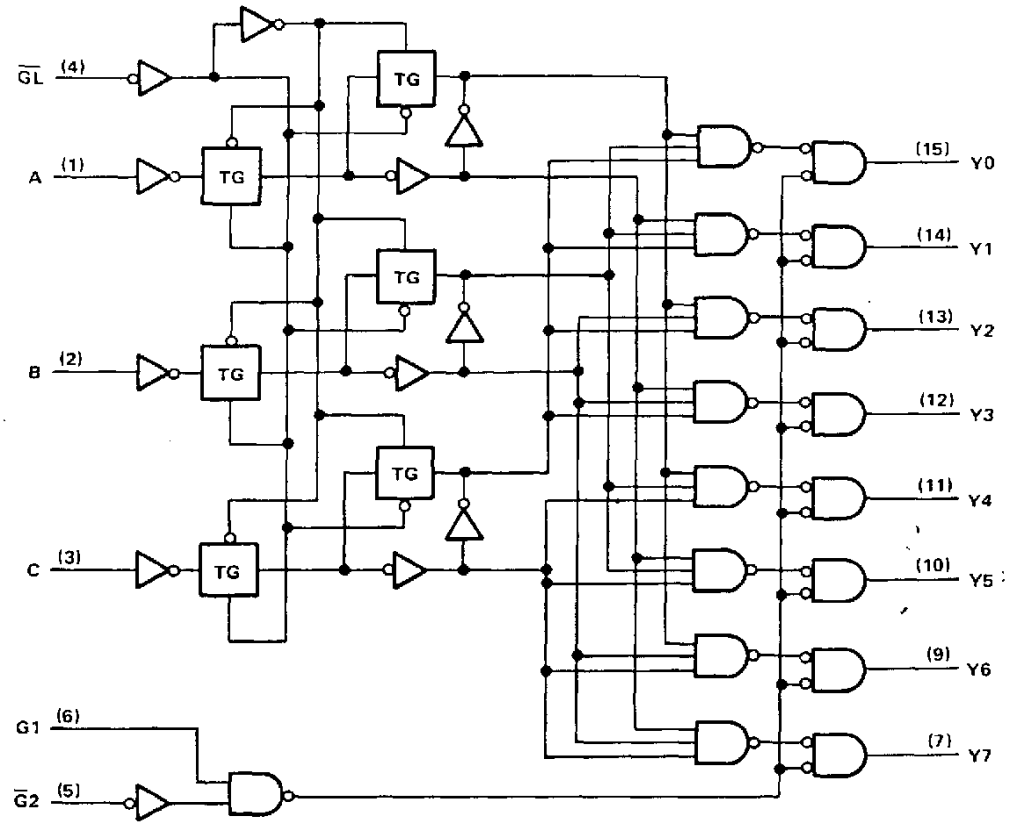
logic diagram (positive logic)



Pin numbers shown are for D, J, and N packages.

FUNCTION TABLE

INPUTS						OUTPUTS							
ENABLE			SELECT										
GL	G1	G2	C	B	A	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
X	X	H	X	X	X	L	L	L	L	L	L	L	L
X	L	X	X	X	X	L	L	L	L	L	L	L	L
L	H	L	L	L	L	H	L	L	L	L	L	L	L
L	H	L	L	L	H	L	H	L	L	L	L	L	L
L	H	L	L	H	L	L	L	H	L	L	L	L	L
L	H	L	L	H	H	L	L	L	H	L	L	L	L
L	H	L	H	L	L	L	L	L	L	H	L	L	L
L	H	L	H	L	H	L	L	L	L	L	H	L	L
L	H	L	H	H	L	L	L	L	L	L	L	H	L
L	H	L	H	H	H	L	L	L	L	L	L	L	H
H	H	L	X	X	X	Outputs corresponding to stored address, L; all others, H							

absolute maximum ratings over operating free-air temperature range†

Supply voltage, V_{CC} . . . . . −0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) . . . . . ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) . . . . . ±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC}) . . . . . ±25 mA
Continuous current through V_{CC} or GND pins . . . . . ±50 mA
Lead temperature 1,6 mm (1/16 in) from case for 60 s: FK or J package . . . . . 300°C
Lead temperature 1,6 mm (1/16 in) from case for 10 s: D or N package . . . . . 260°C
Storage temperature range . . . . . −65°C to 150°C

†Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			SN54HC237			SN74HC237			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		2	5	6	2	5	6	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.5			1.5			V
		V_{CC} = 4.5 V	3.15			3.15			
		V_{CC} = 6 V	4.2			4.2			
V_{IL}	Low-level input voltage	V_{CC} = 2 V	0		0.3	0		0.3	V
		V_{CC} = 4.5 V	0		0.9	0		0.9	
		V_{CC} = 6 V	0		1.2	0		1.2	
V_I	Input voltage		0		V_{CC}	0		V_{CC}	V
V_O	Output voltage		0		V_{CC}	0		V_{CC}	V
t_t	Input transition (rise and fall) times	V_{CC} = 2 V	0		1000	0		1000	ns
		V_{CC} = 4.5 V	0		500	0		500	
		V_{CC} = 6 V	0		400	0		400	
T_A	Operating free-air temperature		−55		125	−40		85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			SN54HC237		SN74HC237		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	$V_I = V_{IH}$ or V_{IL}, I_{OH} = −20 μA	2 V	1.9	1.998		1.9		1.9		V
		4.5 V	4.4	4.499		4.4		4.4		
		6 V	5.9	5.999		5.9		5.9		
	$V_I = V_{IH}$ or V_{IL}, I_{OH} = −4 mA	4.5 V	3.98	4.30		3.7		3.84		
	$V_I = V_{IH}$ or V_{IL}, I_{OH} = −5.2 mA	6 V	5.48	5.80		5.2		5.34		
V_{OL}	$V_I = V_{IH}$ or V_{IL}, I_{OL} = 20 μA	2 V		0.002	0.1		0.1		0.1	V
		4.5 V		0.001	0.1		0.1		0.1	
		6 V		0.001	0.1		0.1		0.1	
	$V_I = V_{IH}$ or V_{IL}, I_{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
	$V_I = V_{IH}$ or V_{IL}, I_{OL} = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
I_I	$V_I = V_{CC}$ or 0	6 V		±0.1	±100		±1000		±1000	nA
I_{CC}	$V_I = V_{CC}$ or 0, I_O = 0	6 V			8		160		80	μA
C_i		2 to 6 V		3	10		10		10	pF

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V_{CC}	T_A = 25°C			SN54HC237		SN74HC237		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, $\overline{GL}$ low	2 V	80			120		100		ns
		4.5 V	16			24		20		
		6 V	14			20		17		
t_{su}	Setup time, A, B, or C before $\overline{GL}$↑	2 V	75			115		95		ns
		4.5 V	15			23		19		
		6 V	13			20		16		
t_h	Hold time, A, B, and C after $\overline{GL}$↑	2 V	5			5		5		ns
		4.5 V	5			5		5		
		6 V	5			5		5		

switching characteristics over recommended operating free-air temperature range (unless otherwise noted), C_L = 50 pF (see Note 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			SN54HC237		SN74HC237		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A, B, C	Any	2 V		91	190		285		240	ns
			4.5 V		23	38		57		48	
			6 V		17	32		48		41	
t_{pd}	$\overline{G}2$	Any	2 V		66	145		220		181	ns
			4.5 V		18	29		44		36	
			6 V		13	25		37		31	
t_{pd}	G1	Any	2 V		68	145		220		181	ns
			4.5 V		18	29		44		36	
			6 V		14	25		37		31	
t_{pd}	$\overline{GL}$	Any	2 V		92	190		285		240	ns
			4.5 V		24	38		57		48	
			6 V		19	32		48		41	
t_t		Any	2 V		38	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

C_{pd}	Power dissipation capacitance	No load, T_A = 25°C	85 pF typ

NOTE 1: Load circuit and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
5962-88606012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SN74HC237N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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